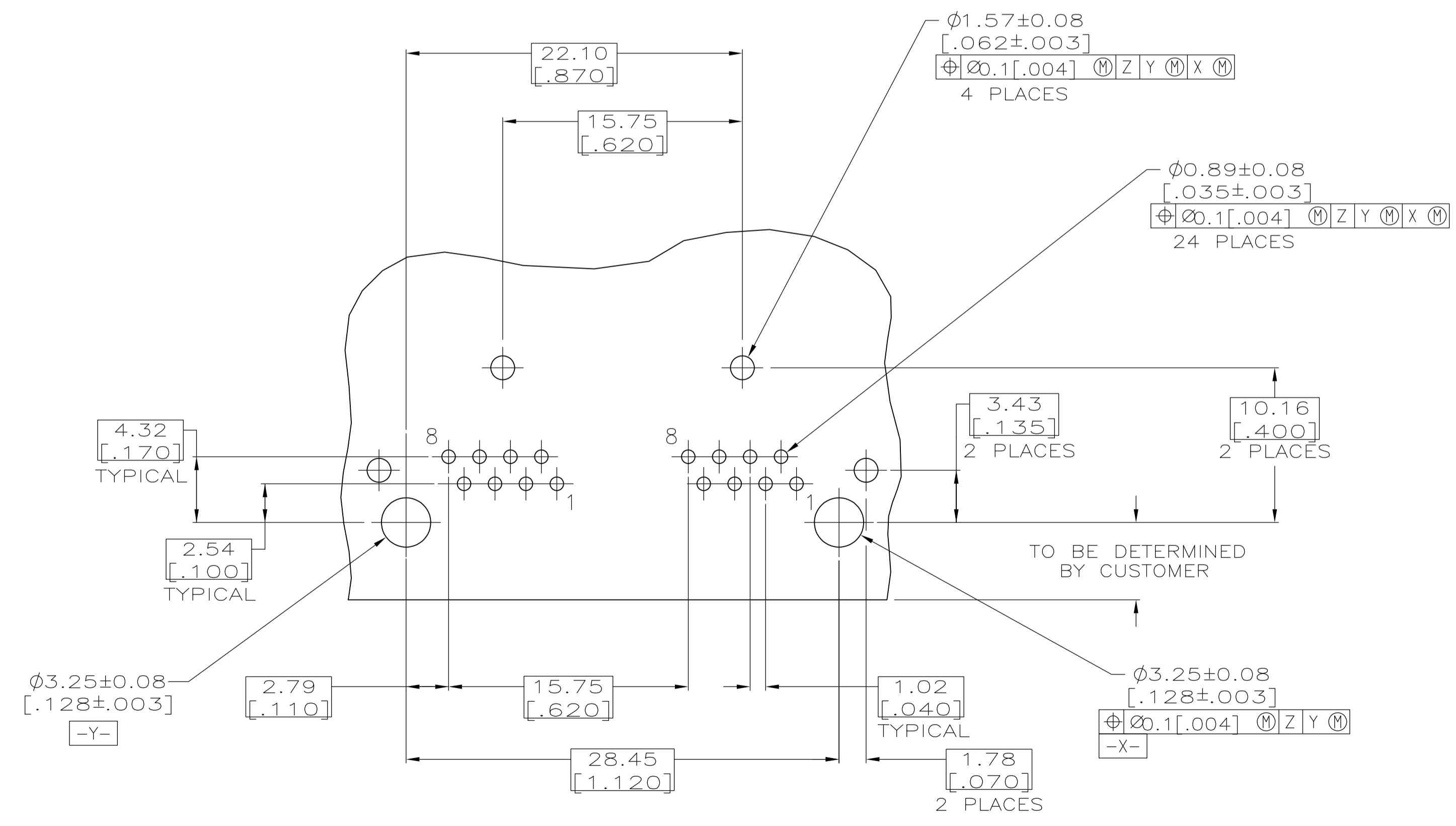


- MATERIAL: HOUSING - HIGH TEMPERATURE THERMOPLASTIC, BLACK, UL94V-0; TERMINALS - 0.36[.014] THICK PHOS BRONZE PLATED WITH 3.81μm[.000150] MINIMUM THICK MATTE TIN IN SOLDER AREA. 1.27 μm [.000050] MINIMUM GOLD IN LOCALIZED PLATE AREA. ENTIRE TERMINAL PLATED WITH 1.27 μm [.000050] MINIMUM THICK NICKEL. SHIELD - 0.196[.0077] THICK COPPER ZINC ALLOY PREPLATED WITH 1.27 μm [.000050] MINIMUM SATIN NICKEL WITH 2.03 μm [.000080] MINIMUM TIN POST DIPPED ON PCB GROUND TABS.
  - JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
- △ SUGGESTED PANEL OPENING DIMENSIONS.  
 △ SUGGESTED CLEARANCE BETWEEN TOP OF CONNECTOR AND TOP PANEL OPENING.
- 5 PARTS PACKAGED IN TAPE&REEL WITH DESICCANT.  
 6 PARTS SUITABLE FOR LEAD FREE REFLOW PROCESSING TO 260° C



SUGGESTED PRINTED CIRCUIT BOARD LAYOUT  
(COMPONENT SIDE)

1932389-1  
PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.		DIN D.ZHU 18JUN2009	Tyco Electronics Corporation Shanghai 200233, P.R.China
DIMENSIONS: mm		CHK M.LI 18JUN2009	
TOLERANCES UNLESS OTHERWISE SPECIFIED:		APVD S.YAO 18JUN2009	NAME
0 PLC ± -			INVERTED MODULAR JACK ASSEMBLY, 1X2, SHIELDED, PANEL GROUND
1 PLC ± -			PRODUCT SPEC
2 PLC ± 0.25(.01)			108-1163-4
3 PLC ± 0.13(.005)			APPLICATION SPEC
4 PLC ± -			114-2154
ANGLES ± -			SIZE CASE CODE DRAWING NO
MATERIAL SEE NOTE 1	FINISH SEE NOTE 1	WEIGHT	RESTRICTED TO
		A1 00779	SCALE 4:1 SHEET 1 OF 1 REV A2
CUSTOMER DRAWING		1932389	

单击下面可查看定价，库存，交付和生命周期等信息

[>>TE Connectivity\(泰科\)](#)